Claims

1. A method for manufacturing a device, said method comprising the step of

- providing a spacer wafer comprising $M \geq 2$ spacer members, wherein M is an integer, each of said M spacer members comprising $N \geq 2$ light channels, N being an integer;

- providing an optics wafer comprising M optics members, each of said M optics members comprising N sets of passive optical components comprising one or more passive optical components each;

- providing a detection wafer comprising M detection members, each of said M detection members comprising N active optical components each;

wherein each of said M spacer members is associated with a different one of said optics members and associated with a different one of said detection members, and

wherein for each of said M spacer members, each of the respective N spacer members is associated with a different one of the N sets of active optical components of the associated optics member and associated with a different one of the N active optical components of the associated detection members, and

wherein for at least one of said M spacer members and the associated optics members and the associated detection members applies that

- all of the N light channels of a respective spacer members provide an identical geometrical path length for light travelling from the associated set of passive optical components of the associated optics member through the respective light channel to the associated active optical component of the associated detection member, and

- at least two of optical path lengths for light travelling from the N sets of passive optical components of a respective optics member through the associated light channel to the associated active optical component are mutually different;

and wherein the method comprises for each of $M \times N$ light channels,:

if the optics member of the respective channel exhibits a manufacturing irregularity:

- gaining a value related to manufacturing irregularities of the respective associated optics member and

- choosing said optical path length in dependence of the respective manufacturing irregularity.

2. The method according to claim 1, wherein the manufacturing irregularities are manufacturing irregularities of the passive optical components of the sets of passive optical components of the respective associated optics member, and wherein the spacer wafer comprises a first layer and a second layer made of different materials.

3. The method according to claim 2, wherein the method comprises a step of adjusting the optical path length by removing material from the second layer.

4. The method according to claim 3, wherein the second layer is made of a polymer material.

5. The method according to claim 1 or 2, comprising a step of fabricating the spacer wafer, the step of fabricating the space wafer comprising steps of

providing a wafer,

locally decreasing a vertical extension of said wafer,

wherein said locally decreasing a vertical extension of said wafer comprises carrying out a first processing step and carrying out subsequently to said first processing step a second processing step different from said first processing step.

6. The method according to claim 5, wherein said first processing step differs from said second processing step in at least one of

an applied processing technique,

a tool used in the respective processing step,

one or more processing parameters used in the respective processing step.

7. The method according to claim 5, wherein said first processing step is carried out at a higher speed of removal of material from a plurality of regions than said second processing step.

8. The method according to claim 5, wherein said first processing step is carried out simultaneously for all path of a spacer member , and said second processing step is carried out separately for different light channels of a spacer member.